

Measurements of 3D/FBK sensors

Alessandro LA ROSA^a

on behalf of

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^a CERN, ^b Fondazione Bruno Kessler (FBK-irst),

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Outline

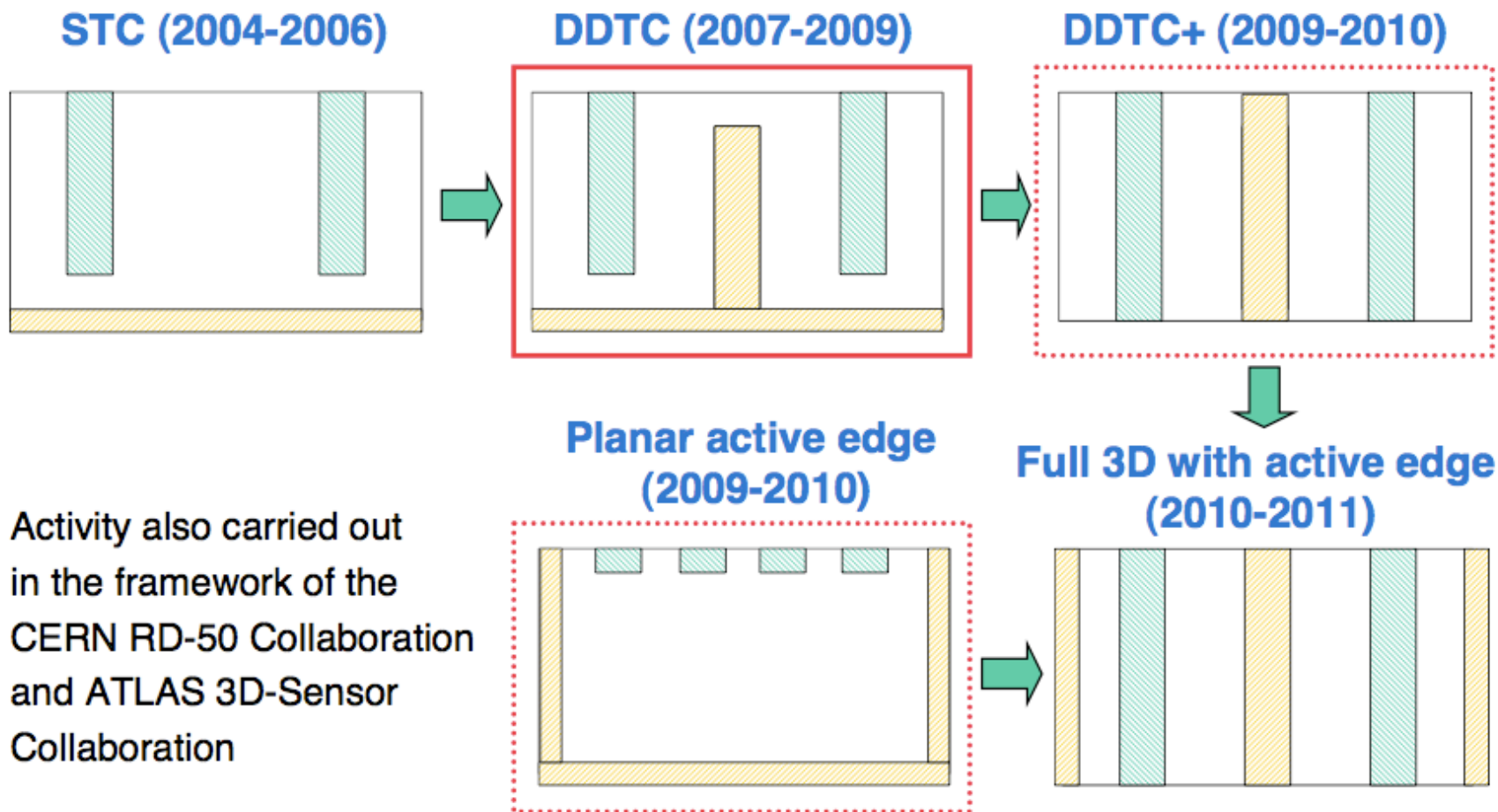
- FBK-irst 3D-Si sensors
- Lab characterization
- Beam tests (performed with ATLAS 3D Collaboration)
- Irradiation
- Conclusions

Parts of this talk have already been presented at HSTD7 (Hiroshima, Sept. 2009), RD09 (Firenze, Oct. 2009) and ATLAS 3D – Rad. Hard. Studies WG Meeting (CERN, Nov. 2009)

- G-F. Dalla Betta et al. *Development of 3D-DDTC pixel detectors for the ATLAS upgrade*. Submitted in NIM A, available at [arXiv:0910.3629](https://arxiv.org/abs/0910.3629)
- A. La Rosa et al. *Preliminary results of 3D-DDTC pixel detectors for the ATLAS upgrade*. PoS (RD09)032 available at [arXiv:0910.3788](https://arxiv.org/abs/0910.3788)
- A. La Rosa. *Irradiation activities at CERN*. Available at <https://twiki.cern.ch/twiki/pub/Main/CernAtlasPixelSensorsRD/3D-RadHardWG.pdf>

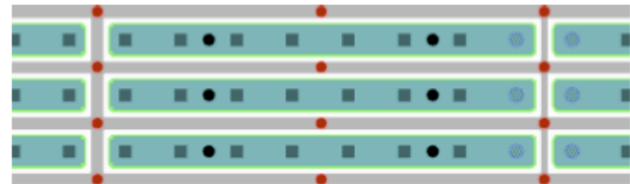
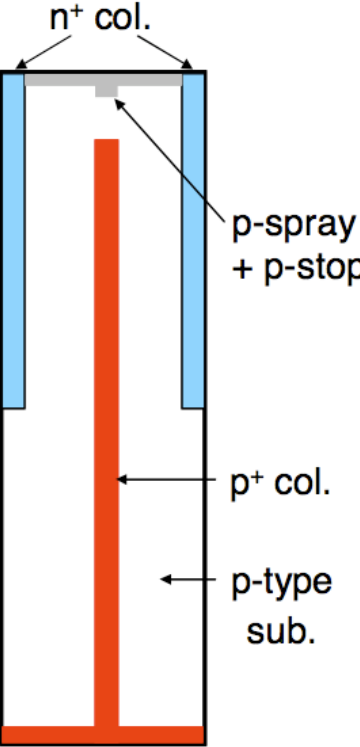
Sensors development / TRENTO

FBK/INFN/PAT agreement (since 2004) and CSN5 projects (since 2005)

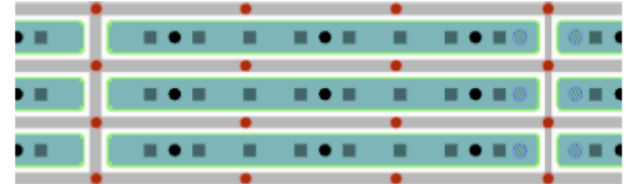


3D-Double side Double Type Column

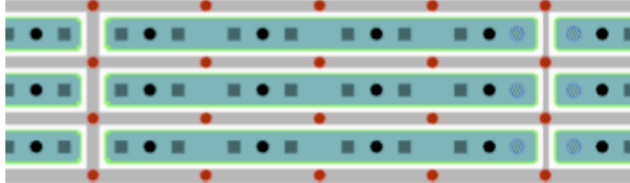
ATLAS PIXEL SENSORS DESIGN



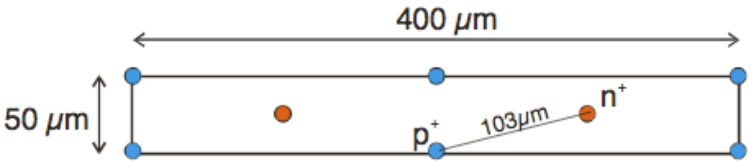
2 junction columns/pixel



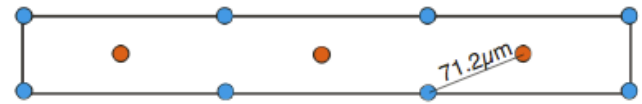
3 junction columns/pixel



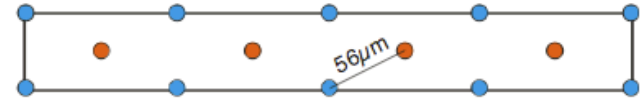
4 junction columns/pixel



2E



3E



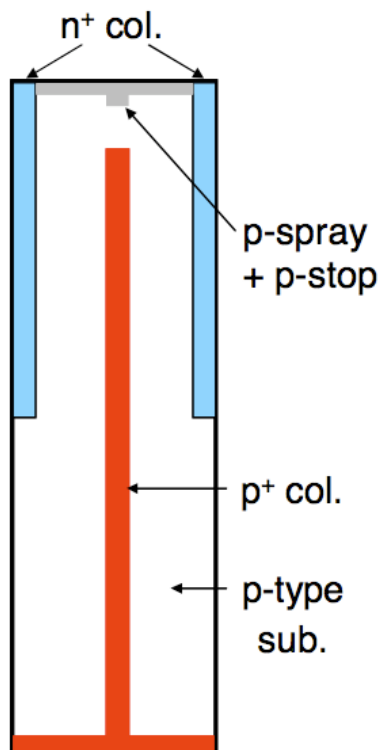
4E

3D-Double side Double Type Column

ATLAS PIXEL SENSORS DESIGN

Two batches so far fabricated for ATLAS – FEI3

- 3D-DCT-2 (p-type substrate, 200 μm , IBS (Fr) DRIE)
- 3D-DTC-2B (p-type substrate, 200 μm , in-house DRIE)



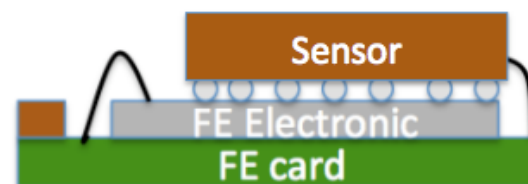
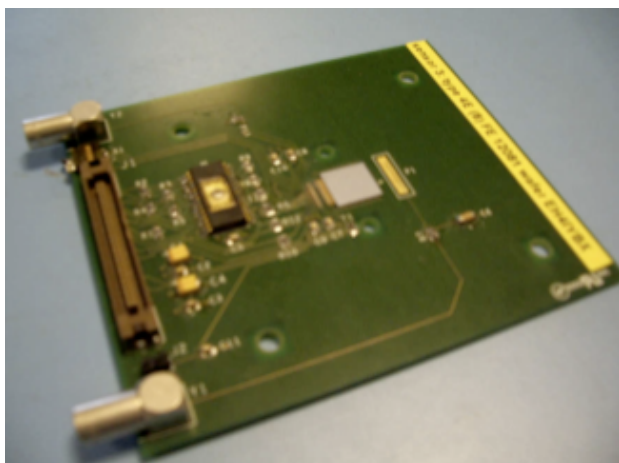
| Parameter | Unit | Value | |
|---------------------------|---------------|----------|-----------|
| | | 3D-DCT-2 | 3D-DTC-2B |
| Substrate thickness | μm | 200 | 200 |
| Junction column thickness | μm | 100 -110 | 140 -170 |
| Ohmic column thickness | μm | 180 -190 | 180 - 190 |
| Column overlap | μm | 90 - 100 | 110 -150 |

Depletion Voltage:

- 3D-DCT-2: -12V
- 3D-DTC-2B : - 4V

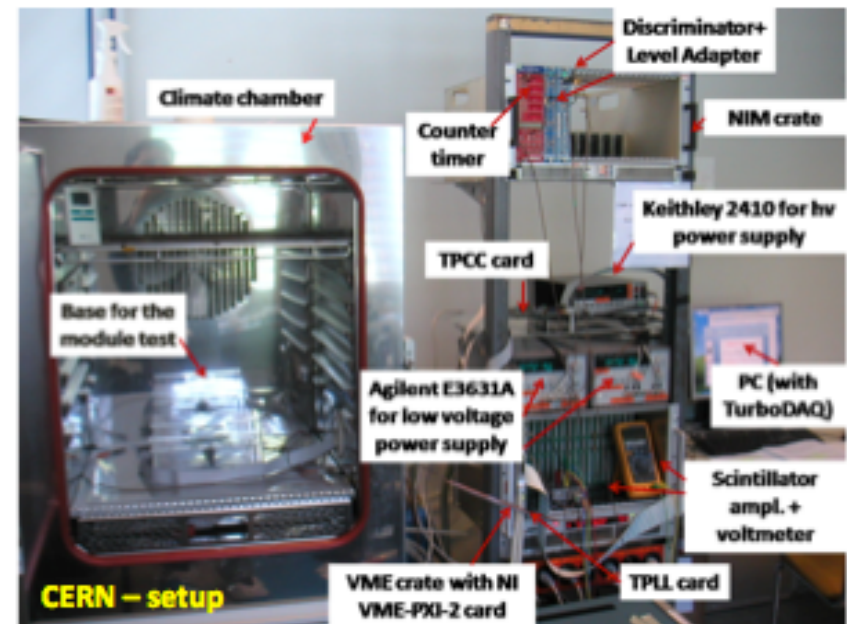
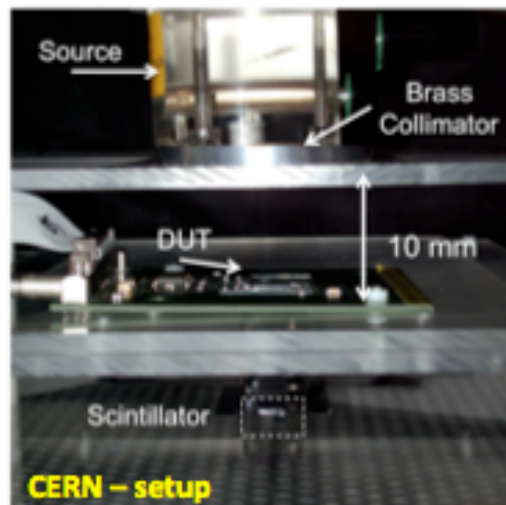
3D-DDTC assemblies with FEI3

- Bump-bonding at SELEX S.I. (Roma, It.)
 - Indium based technology
 - 22 from batch DTC-2
 - 20 from batch DTC-2B
 - Few of these sensors have been flip-chipped on ATLAS chip FEI3



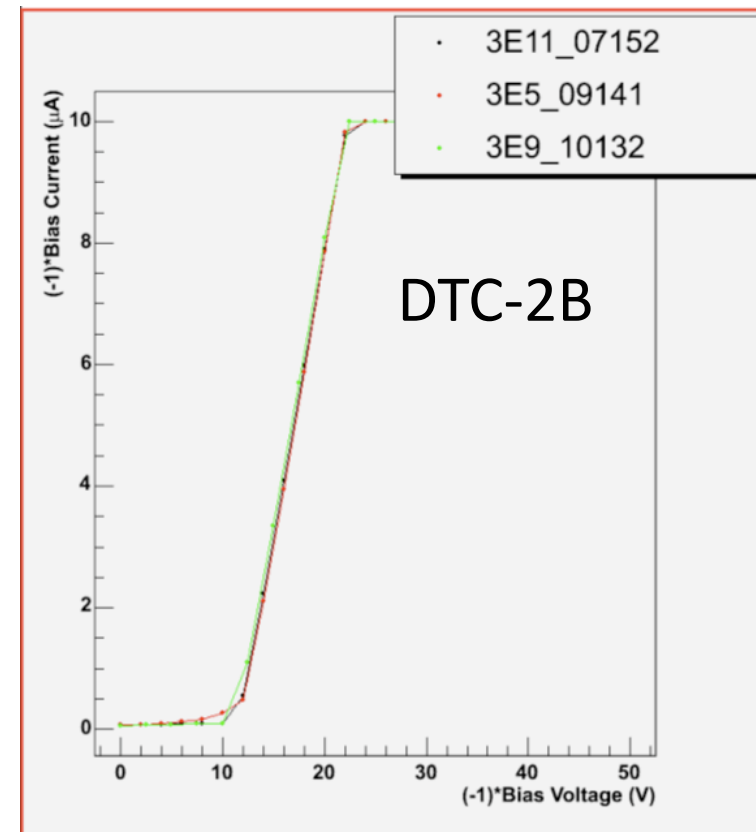
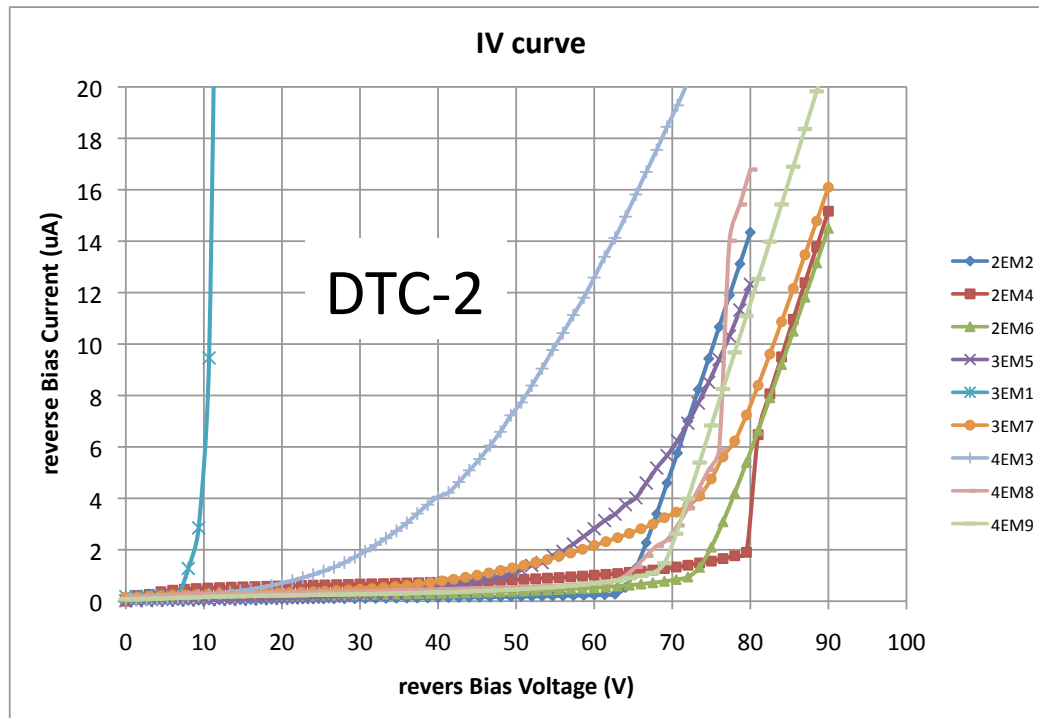
Experimental setup

- Tests made at CERN and INFN/Genova
- Pixel test station based on ATLAS TurboDAQ system
- Measurements
 - Electrical and noise tests
 - Response to radioactive sources
 - Gamma: Am241 and Cd 109 → self triggered
 - Beta: Sr90 → triggered by scintillator

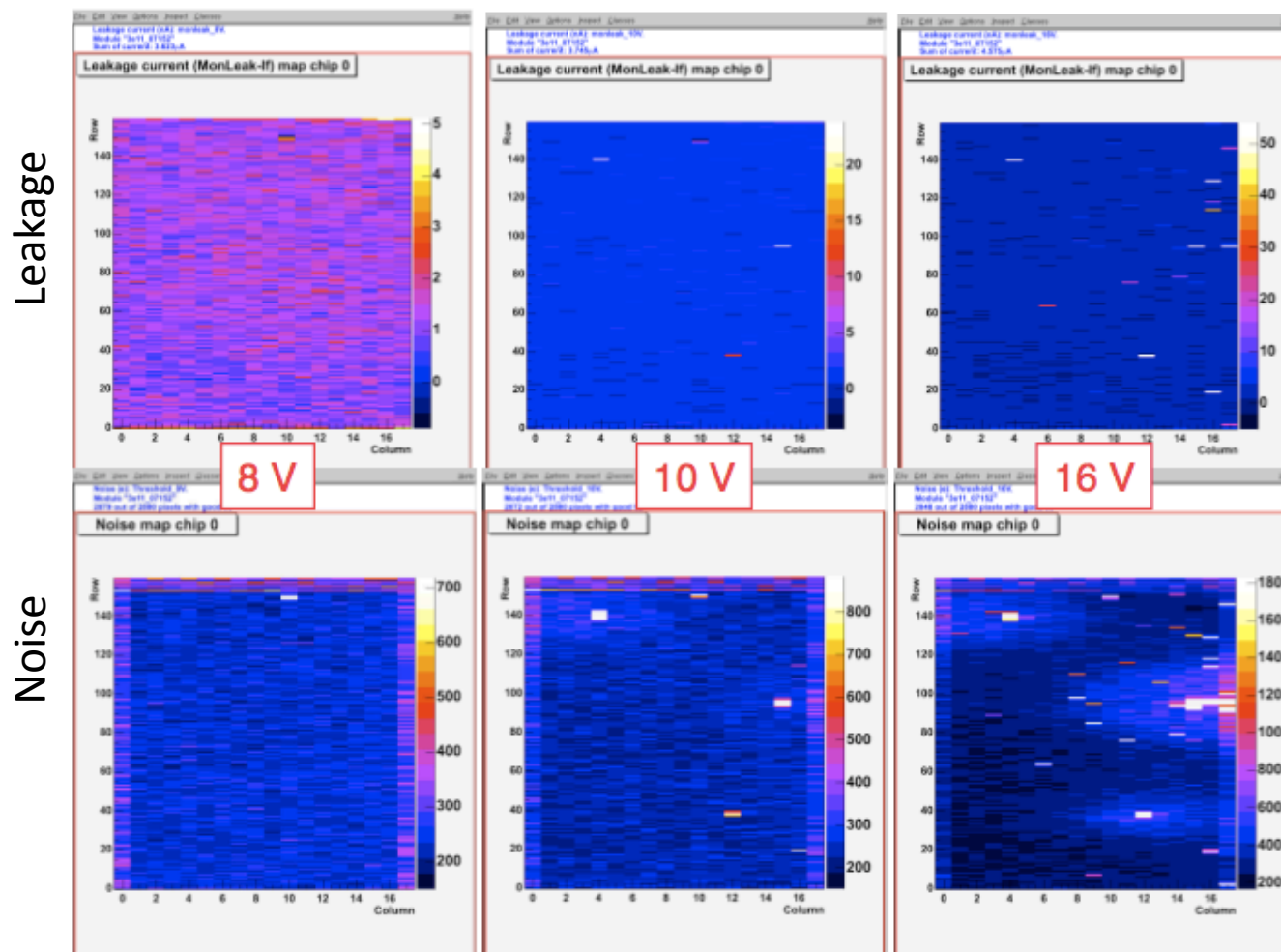


Leakage current

- DTC-2
- DTC-2B systematically early breakdown



DTC-2B: early breakdown problem



Early breakdown related to presence of local effects

At about -10V the leakage current starts to rise and a few pixels become very noisy compared to the others.

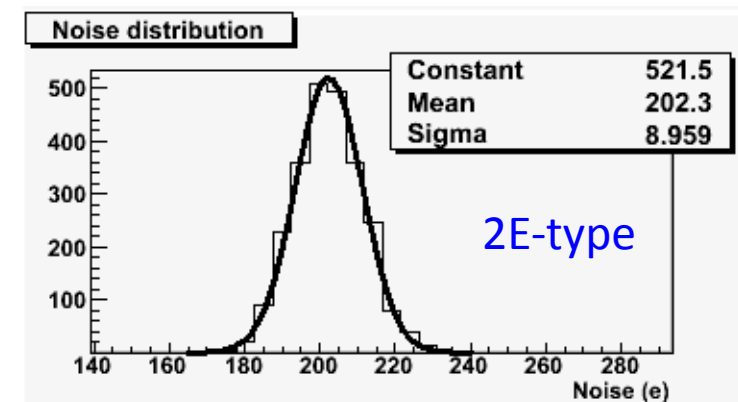
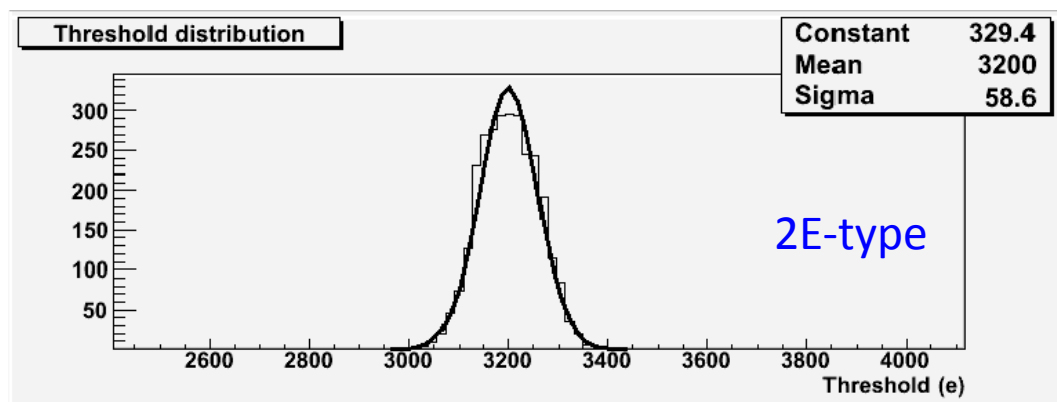
Increasing the bias voltage the number of noisy pixels increases.

Maybe some damage occurred during the assembly → Still to be understood

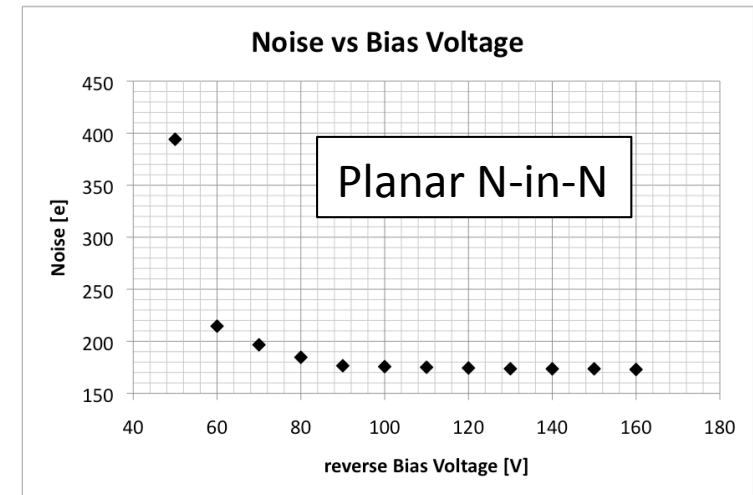
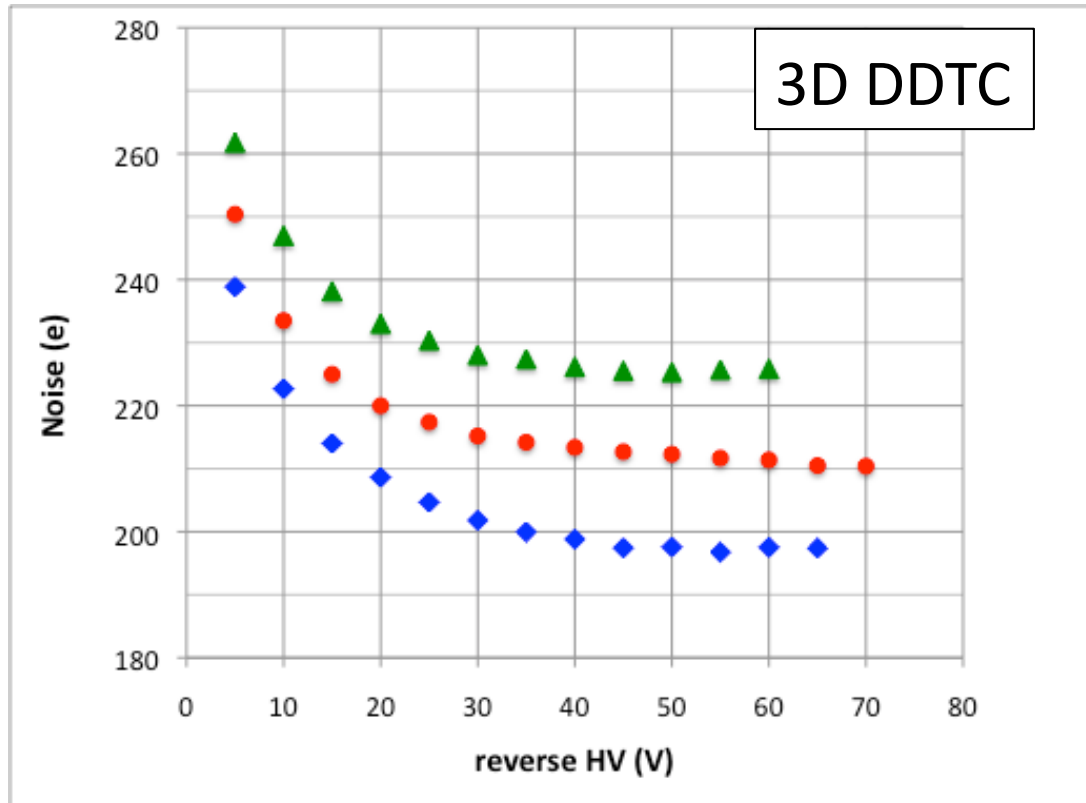
Threshold and noise measurements

FE Tuned with Th=3k2e- and 60 ToT @ 20ke-

| sensor | Threshold (e) | Noise (e) | HV |
|--------|---------------|---------------|------|
| FBK-2E | 3200 ± 58.6 | 202.3 ± 8.96 | -35 |
| FBK-3E | 3318 ± 42.02 | 206.6 ± 8.29 | -35 |
| FBK-4E | 3284 ± 41.27 | 229.8 ± 9.87 | -35 |
| N-in-N | 3259 ± 42.96 | 181.1 ± 9.367 | -150 |



Noise vs Bias Voltage

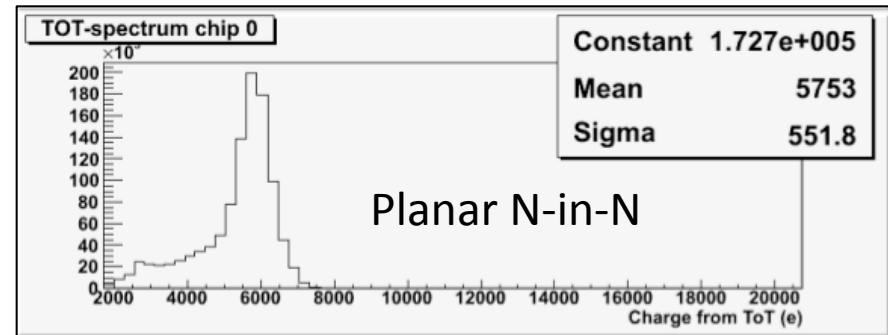
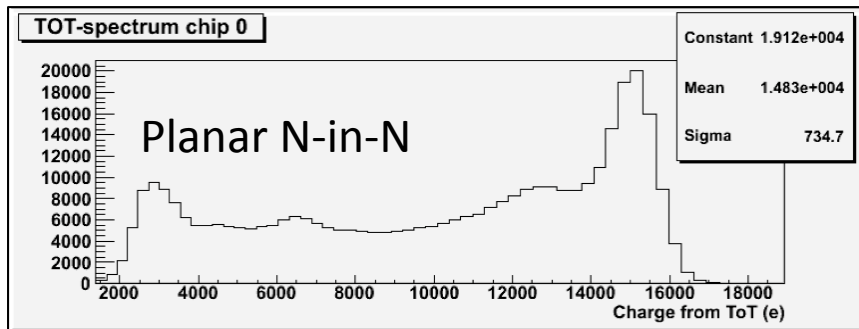
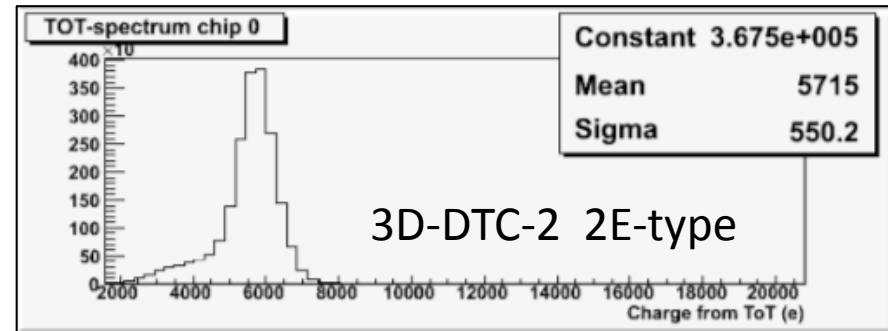
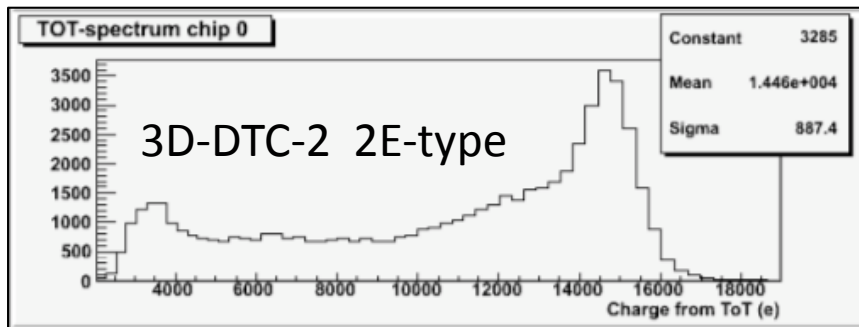


- ▲ 2 electrodes per pixel
- 3 electrodes per pixel
- 4 electrodes per pixel

*Measurements at climate chamber setup:
20 °C and relative humidity of 12%.*

Gamma source test

Spectrum as a sum over all pixel without any clustering



Am241

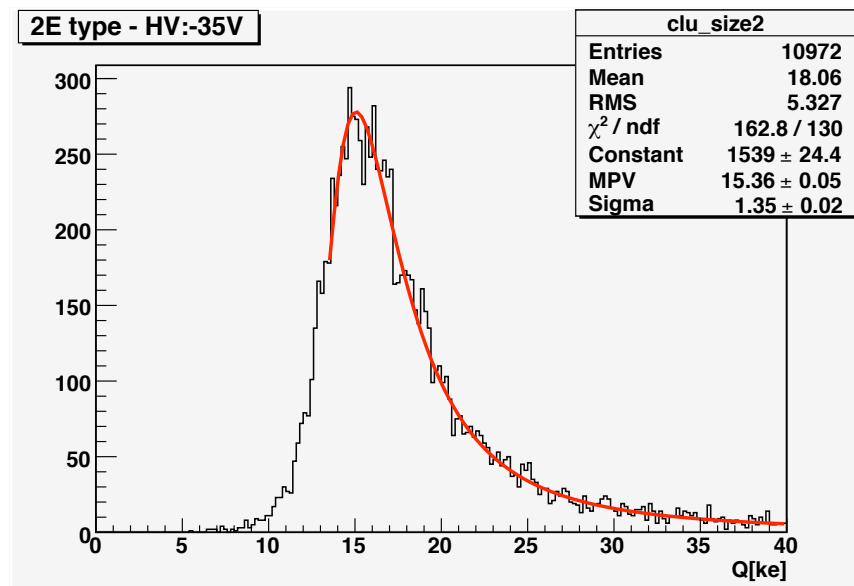
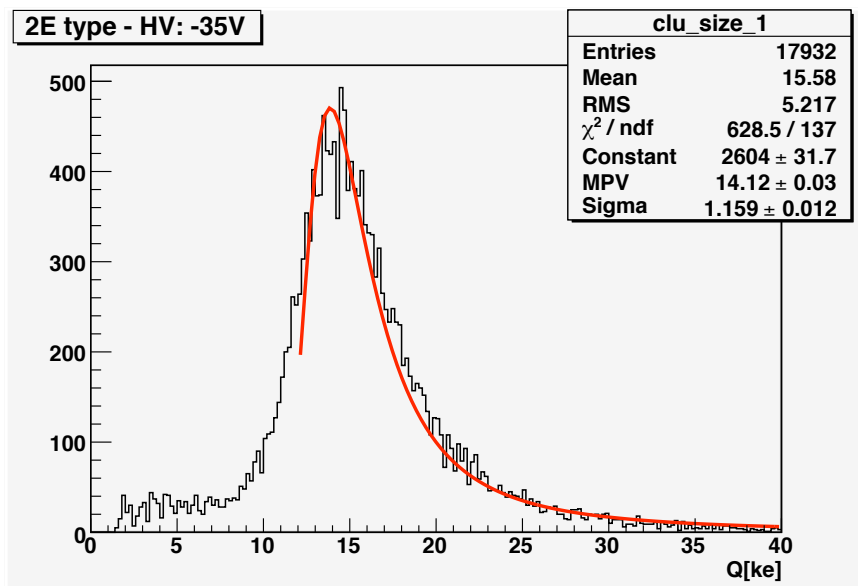
See the expected 60keV peak

Cd109

See the expected 23keV peak

Beta source tests (Sr90)

3D-DDTC: 200 μm thickness

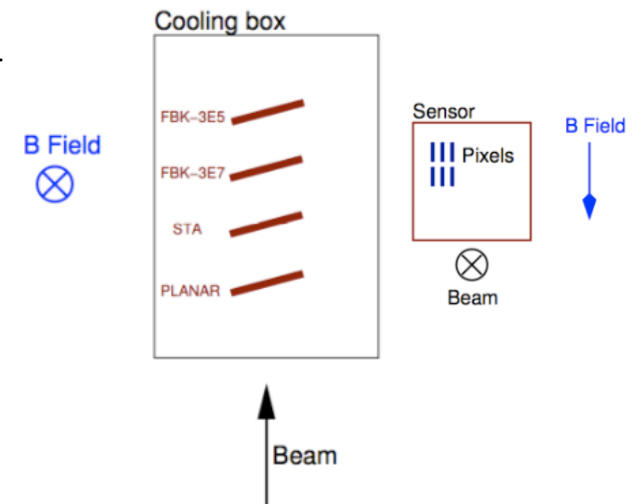


| Sensor type | MPV clu.size.1 (ke-) | MPV clu.size 2 (ke-) |
|-----------------------------|----------------------|----------------------|
| 3D-2E | 14.12 ± 0.03 | 15.36 ± 0.05 |
| 3D-3E | 14.07 ± 0.03 | 15.25 ± 0.02 |
| 3D-4E | 14.07 ± 0.03 | 15.25 ± 0.03 |
| Planar (250 μm) | 17.19 ± 0.18 | 18.52 ± 0.06 |

Beam Tests at CERN

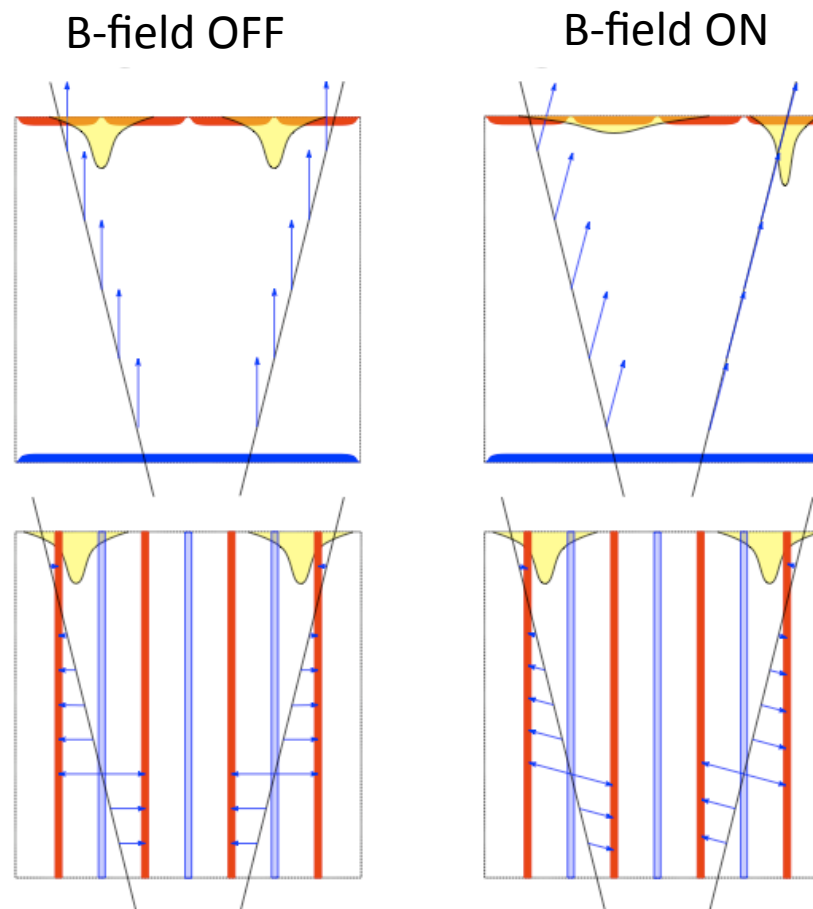


- In the framework of ATLAS 3D Collaboration
 - Study the ATLAS 3DSi pixels in the operational conditions of ATLAS Inner Detector
- The beam line (CERN North Area – H8)
 - 180 GeV π^+ from SPS
 - *Morpurgo* magnet: Vertical field, max strength: (1.35 ± 0.10) T, large bore dipole: 4m x 1.6m ϕ
 - Used for ATLAS Inner Tracker characterization
- The Detectors Under test
 - N-in-N Planar Pixel sensor (reference sensor) -HV= -150V -
 - Stanford full 3D sensor (3E-type) -HV= -35V -
 - FBK – DTC-2 (3E-type) -HV= -35V -
 - FBK – DTC-2B (3E-type) -HV= -8V -
- Configuration
 - DUTs with no tilt, magnetic field ON and OFF
 - DUTs with 15° nominal tilt, magnetic field ON and OFF



Effect of Magnetic Field

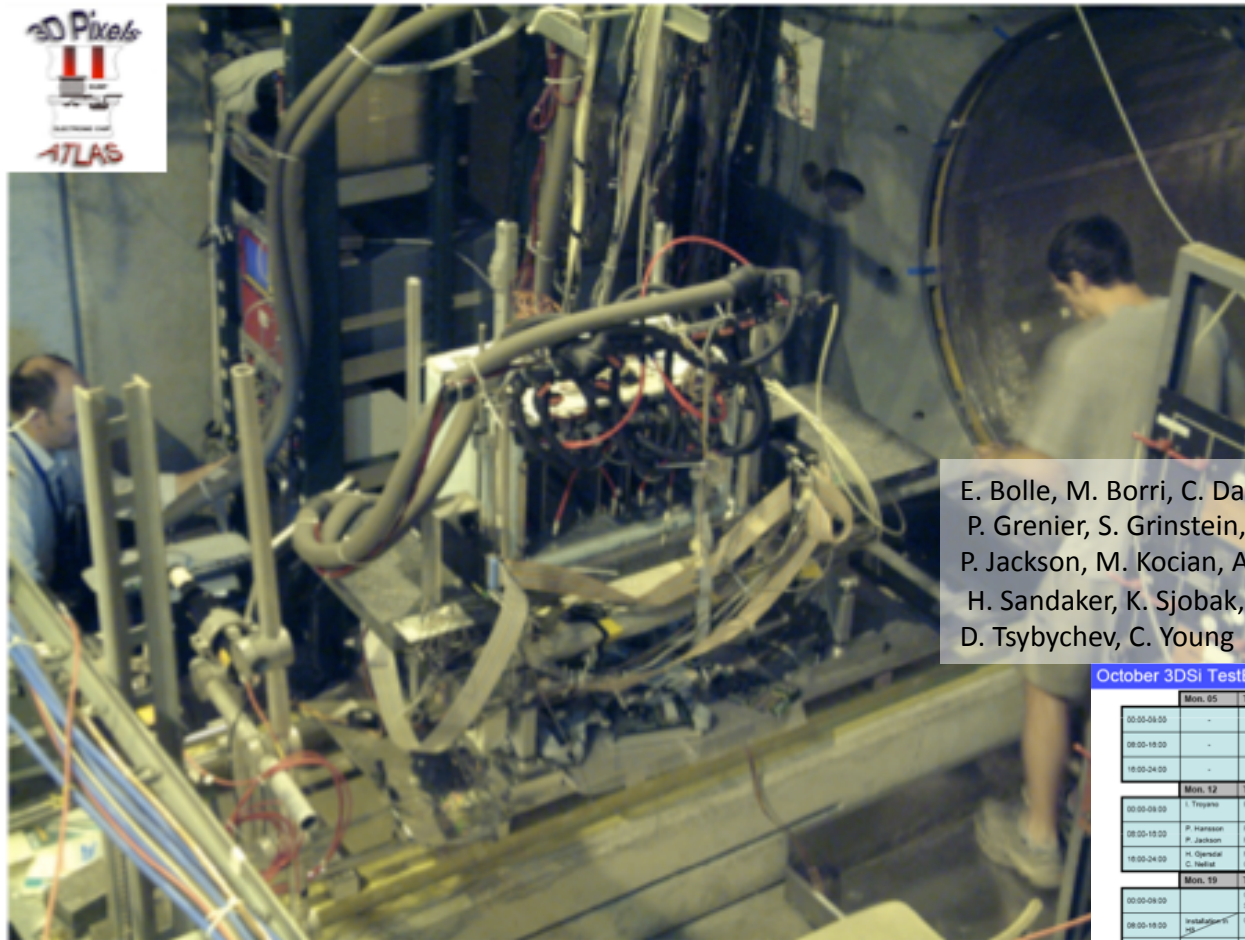
- Planar sensors
 - E and B fields are orthogonal
 - Lorentz force orthogonal to drift
 - Focus or de-focus charge cloud
 - Cluster size minim. at Lorentz angle



- 3D sensors
 - E and B fields are coplanar (lateral)
 - Lorentz force act out of the lateral plane
 - Minimal effect on charge cloud

→ Expect small effect for 3D sensors

Experimental area



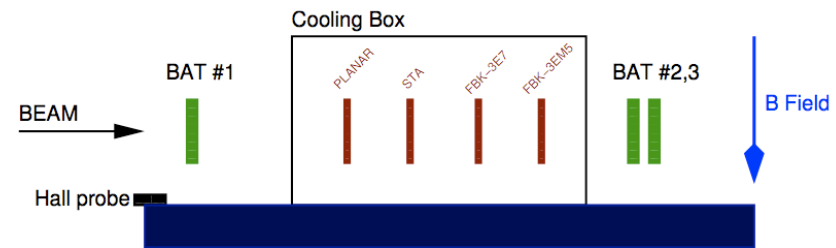
E. Bolle, M. Borri, C. Da Via, S. Dong, S. Fazio,
 P. Grenier, S. Grinstein, H. Gjerdsdal, P. Hansson,
 P. Jackson, M. Kocian, A. La rosa, F. Rivero, O. Rohne,
 H. Sandaker, K. Sjobak, T. Slavicek, J.-W. Tsung,
 D. Tsybychev, C. Young

October 3DSI TestBeam Shift List

| Mon. 05 | Tues. 06 | Wed. 07 | Thur. 08 | Frid. 09 | Sat. 10 | Sun. 11 |
|-------------|------------------------------|----------------------------|----------------------------|-----------------------------|-----------------------------|------------------------------|
| 00:00-08:00 | - | - | D. Rohne D. Silvertan | D. Rohne D. Silvertan | D. Rohne D. Silvertan | I. Troyano I. Troyano |
| 08:00-18:00 | - | - | P. Hansson H. Gjerdsdal | P. Hansson M. Gordini | P. Hansson H. Gjerdsdal | P. Grenier M. Gordini |
| 18:00-24:00 | - | - | I. Troyano P. Grenier | A. La Rosa M. Gordini | A. La Rosa M. Gordini | H. Gjerdsdal C. Hellat |
| Mon. 12 | Tues. 13 | Wed. 14 | Thur. 15 | Frid. 16 | Sat. 17 | Sun. 18 |
| 00:00-08:00 | I. Troyano | I. Troyano | D. Rohne | D. Rohne | K. Sjobak | S. Grinstein I. Troyano |
| 08:00-18:00 | P. Hansson P. Jackson | M. Borri P. Jackson | C. Barnea A. La Rosa | C. Da Via A. La Rosa | M. Chreassani P. Grenier | M. Chreassani J. Balbuena |
| 18:00-24:00 | H. Gjerdsdal C. Hellat | P. Grenier C. Hellat | I. Troyano P. Grenier | S. Grinstein M. Borri | C. Barnea C. Da Via | C. Barnea M. Borri |
| Mon. 19 | Tues. 20 | Wed. 21 | Thur. 22 | Frid. 23 | Sat. 24 | Sun. 25 |
| 00:00-08:00 | D. Rohne S. Grinstein | D. Rohne S. Grinstein | D. Rohne S. Grinstein | D. Rohne S. Grinstein | K. Halle | K. Halle |
| 08:00-18:00 | Installation J. Shupak | C. Fleta | C. Fleta | C. Fleta | M. Gordini C. Da Via | M. Gordini J. Shupak |
| 18:00-24:00 | M. Chreassani J. Balbuena | I. Troyano J. Balbuena | I. Troyano J. Balbuena | H. Gjerdsdal J. Balbuena | H. Gjerdsdal A. Moadi | A. Moadi |
| Mon. 26 | Tues. 27 | Wed. 28 | Thur. 29 | Frid. 30 | Sat. 31 | Sun. 01 |
| 00:00-08:00 | - | - | - | - | - | - |
| 08:00-18:00 | J. Shupak | J. Shupak | J. Shupak | P. Grenier | D. Silvertan | D. Silvertan P. Grenier |
| 18:00-24:00 | A. Moadi H. Gjerdsdal | S. DeWilde H. Gjerdsdal | P. Hansson H. Gjerdsdal | P. Grenier H. Gjerdsdal | P. Grenier | |

Beam Telescope and Tracking

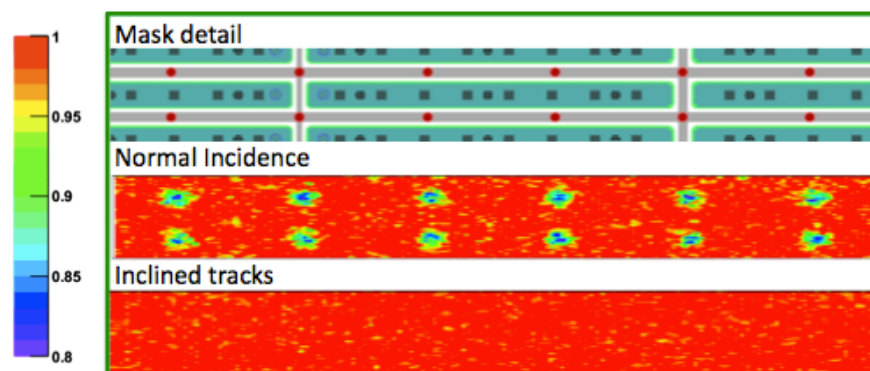
- **Bonn ATLAS Telescope**
 - Two-sided Si micro-strip sensors
 - Strip pitch: 50 μm
 - Analog read-out
 - Integrated DAQ and on-line DQ system
 - Position resolution $\sim 5\mu\text{m}$
 - Masked noisy strips
- **Trigger system**
 - Two scintillators in coincidence
 - Trigger Veto – anti coincidence
 - Trigger phase measurements (TDC)
- **Magnetic field tracking**
 - Using 3 telescope planes
 - Approximate field as homogeneous
- **Data Analysis performed with:**
 - **H. Gjersdal** and **O. Rohne** / **Oslo**
 - **P. Hansson** and **P. Grenier** / **SLAC**



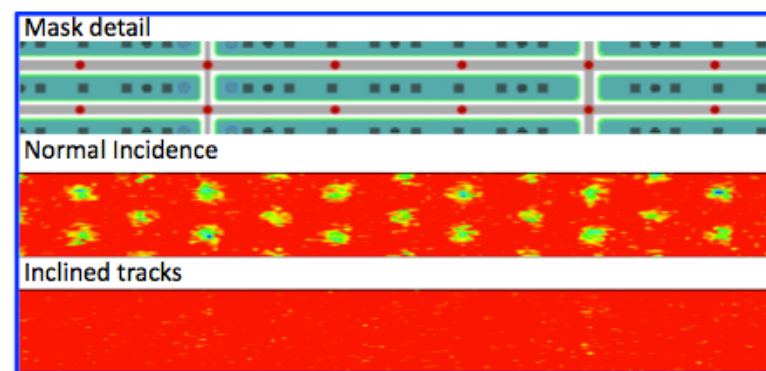
3D-DDTC - Preliminary results

- Hit Efficiency

To show the hit efficiency as function of the track position all tracks have been studied and the track position has been folded into a 2x2 cell ($800\mu\text{m} \times 100\mu\text{m}$).



DTC-2: 90-100um Column Overlap

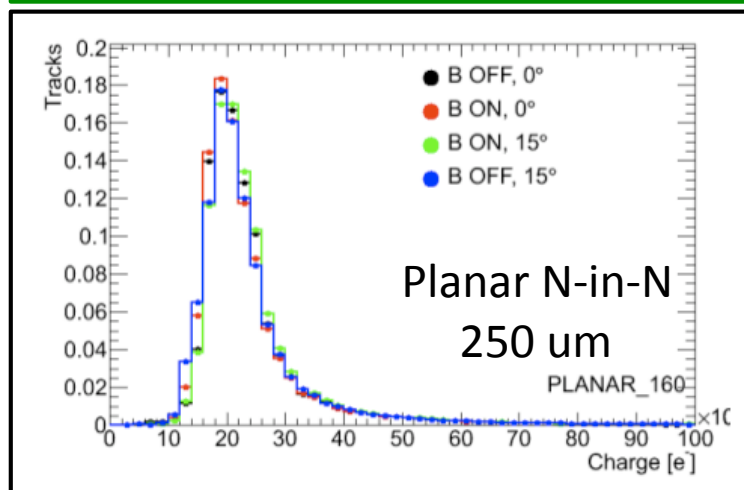
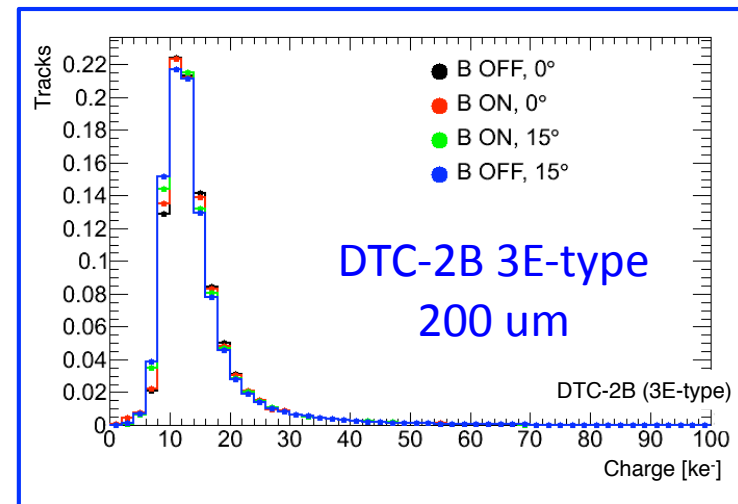
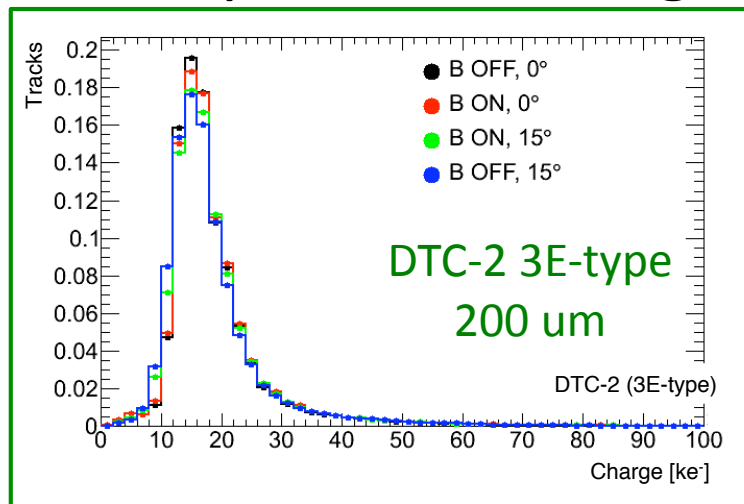


DTC-2B: 110-150um Column Overlap

| DUTs | B off | | B on | |
|------------------|------------------|-------------------|------------------|-------------------|
| | $\phi = 0^\circ$ | $\phi = 15^\circ$ | $\phi = 0^\circ$ | $\phi = 15^\circ$ |
| DTC-2 (3E-type) | 98.38±0.03 | 99.82±0.01 | 98.34±0.03 | 99.49±0.01 |
| DTC-2B (3E-type) | 99.21±0.02 | 99.82±0.004 | 99.14±0.02 | 99.945±0.004 |

3D-DDTC - Preliminary results

- Most probable charge distribution



*DTC-2B lower charge than DTC-2 !!!!!
Operated with a lower bias voltage (-8 V)
due to its early breakdown problems*

*DTC-2 and Planar N-in-N ...
different charge collected in according to
different sensors thickness !!*

3D-DDTC - Preliminary results

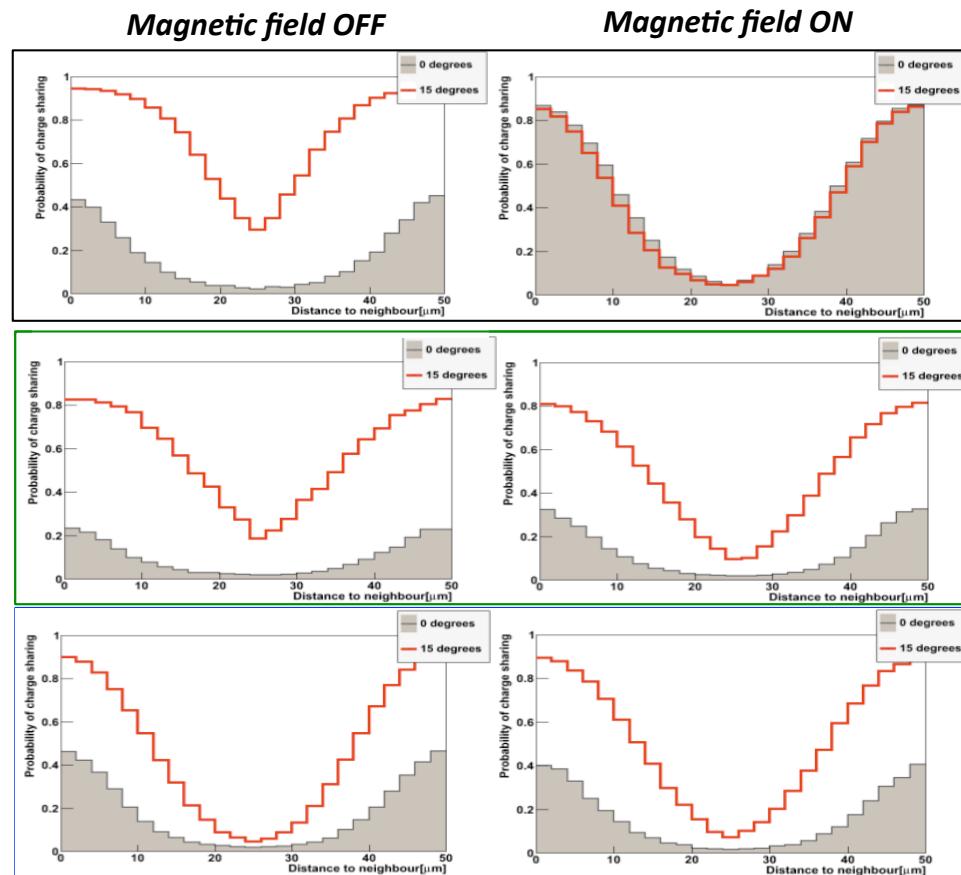
- Charge sharing probability (50 μm direction)

Defined as as the probability that one of the relative neighbors of the pixel cell the track passes through has gone above threshold, given that the pixel cell where the track passes through has gone above threshold

Planar
N-in-N

DTC-2
3E-type

DTC-2B
3E-type



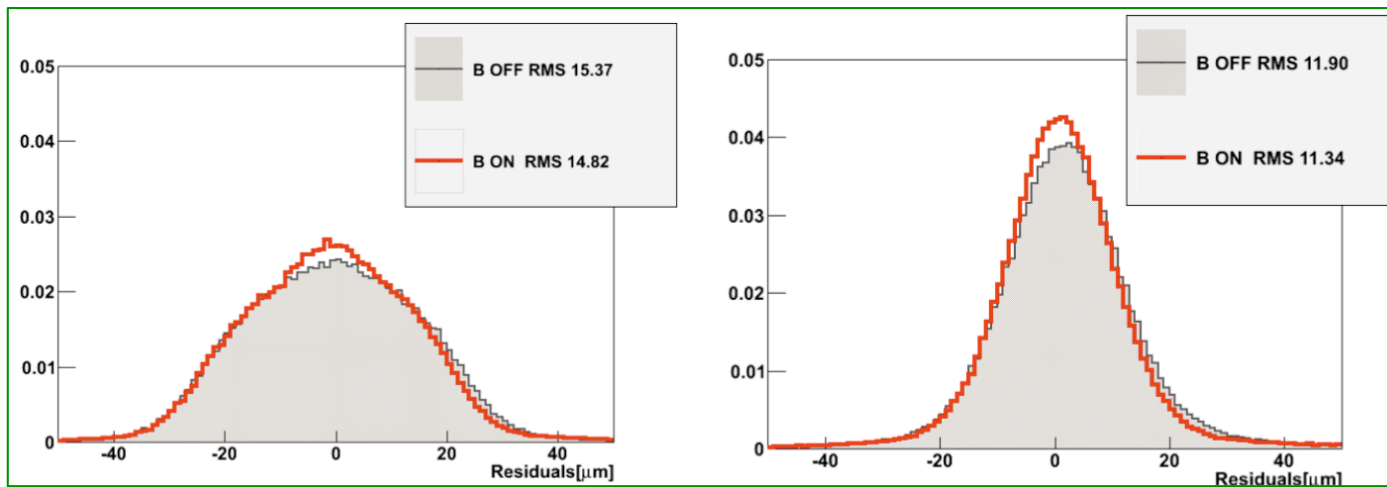
3D-DDTC - Preliminary results

- Track residual distribution (50 μm direction)

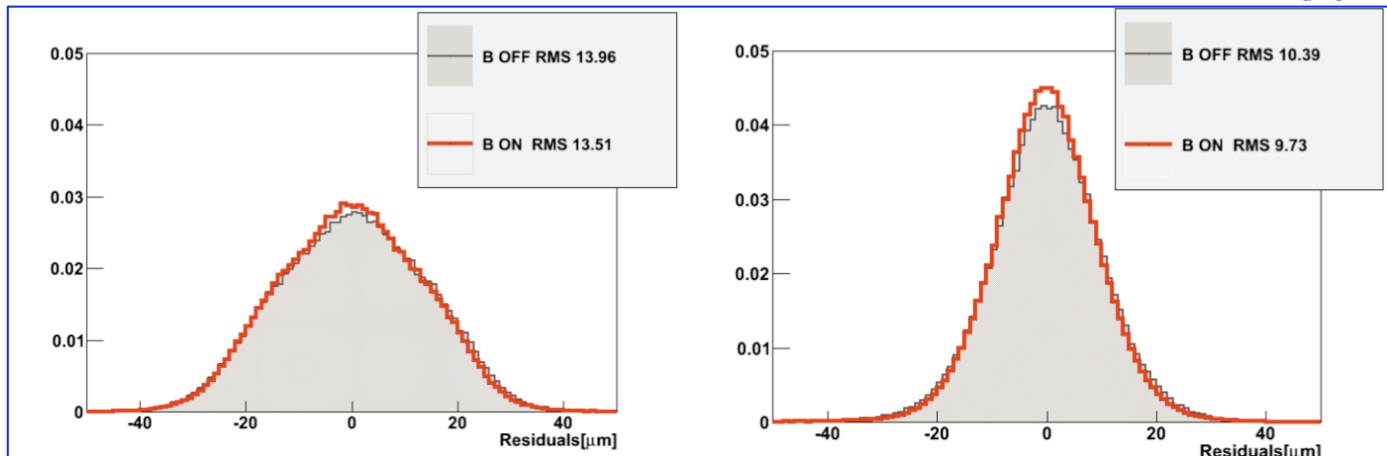
Perpendicular tracks

Inclined tracks

DTC-2
3E-type



DTC-2B
3E-type

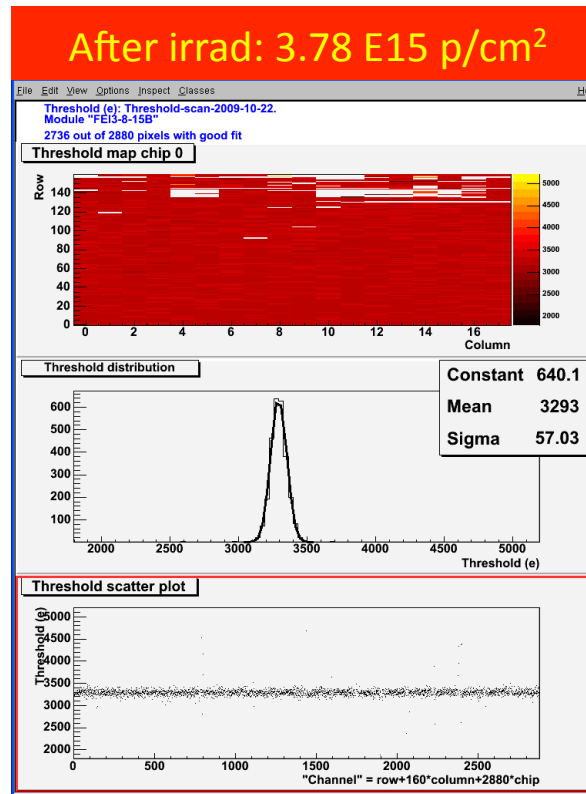
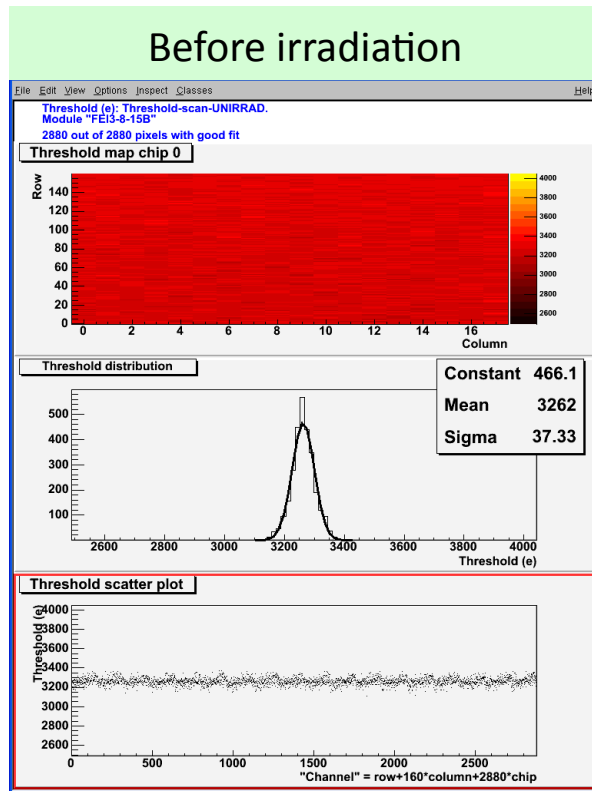


CERN Irradiation plans

- **Pre-Irradiation tests**
 - For DUTs : IV scan, Monleak scan, Threshold&Noise, ToT Calib, Source tests: Am²⁴¹ and Cd¹⁰⁹ (self-triggered) and Sr⁹⁰ (external triggered)
- **Front-end electronics irradi tests (CERN – IRRAD-1)**
 - We know the FEI3 should work after a tot fluences irradi of $\sim 4 \text{ E15 p/cm}^2$
 - Study its behavior at different higher fluences ($\sim 5\text{-}6 \text{ E15 p/cm}^2$) in several steps.
 - Already tested up to 3.78 E15 p/cm^2 at IRRAD-3.
- **Detectors (FE+sensor) irradi tests (CERN – IRRAD-3)**
 - Silicon 3D (FBK-dtc2) and planar Silicon sensors (N-in-N).
 - Study their behavior at different fluences (up to 4 E15 p/cm^2)
- **Post-Irradiation tests**
 - For DUTs : IV scan, Monleak scan, Threshold&Noise, ToT Calib, Source tests: Am²⁴¹ and Cd¹⁰⁹ (self-triggered) and Sr⁹⁰ (external triggered).
 - ATLAS 3D and PPS beam tests (2010) at CERN SPS.

FEI3 irradiation: preliminary results

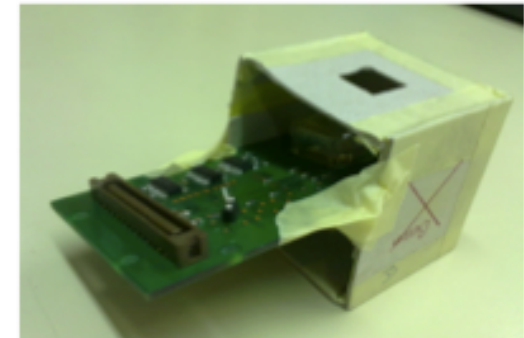
FE Tuned at 60 ToT @ 20ke- with a Threshold of 3k2-



CERN – IRRAD 1

FE No biased

FE retuned
after irradiation

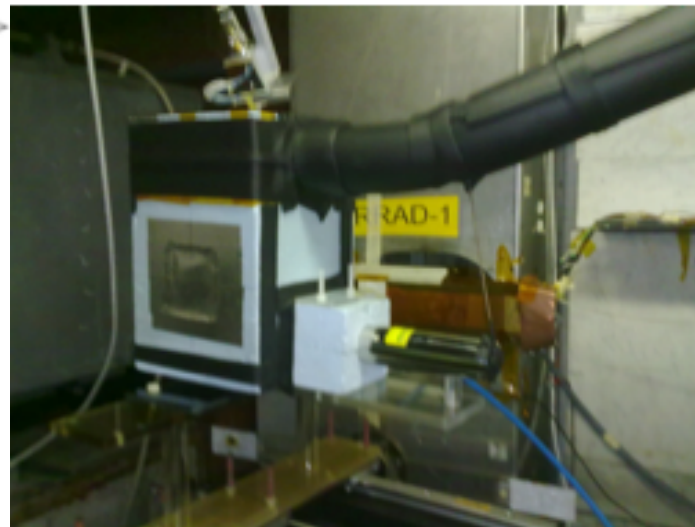
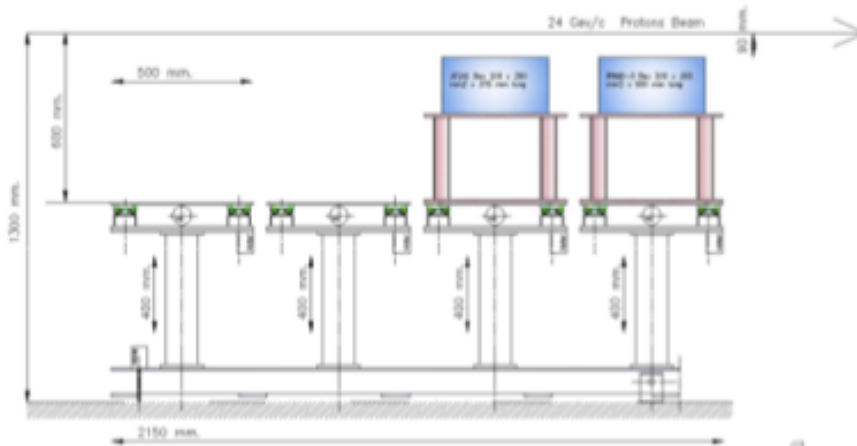
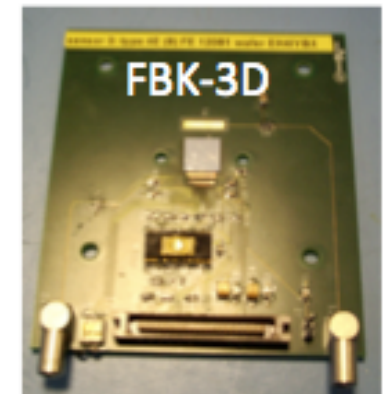


| | BEFORE IRRAD | AFTER IRRAD (3.78 E15 p/cm ²) |
|---------------|--------------|---|
| Threshold (e) | 3262 ± 37.33 | 3293 ± 57.03 |
| Noise (e) | 101.8 ± 8.3 | 105.5 ± 8.12 |
| ToT (e) | 61.67 ± 1.84 | 59.85 ± 2.42 |

Thanks to:
N. Wermes and F. Hugging for FE-I3 availability
and M. Gleser and F. Rivero for irradiation
support

SCA Irradiation

- DUTS: Planar (n-in-n) pixel sensor and 3D-DDTC (FBK)
- DUTs biased
- Low temperature (-14C)
- Fluence up to $4 \text{ E}15 \text{ p/cm}^2$



Thanks to M. Gleser and F. Rivero for irradi. supporter

Nov. 18, 2009

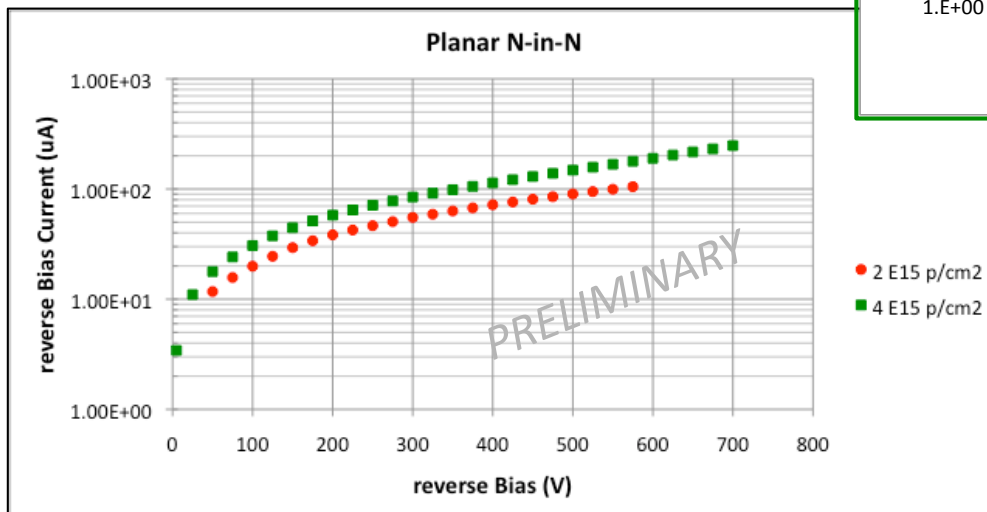
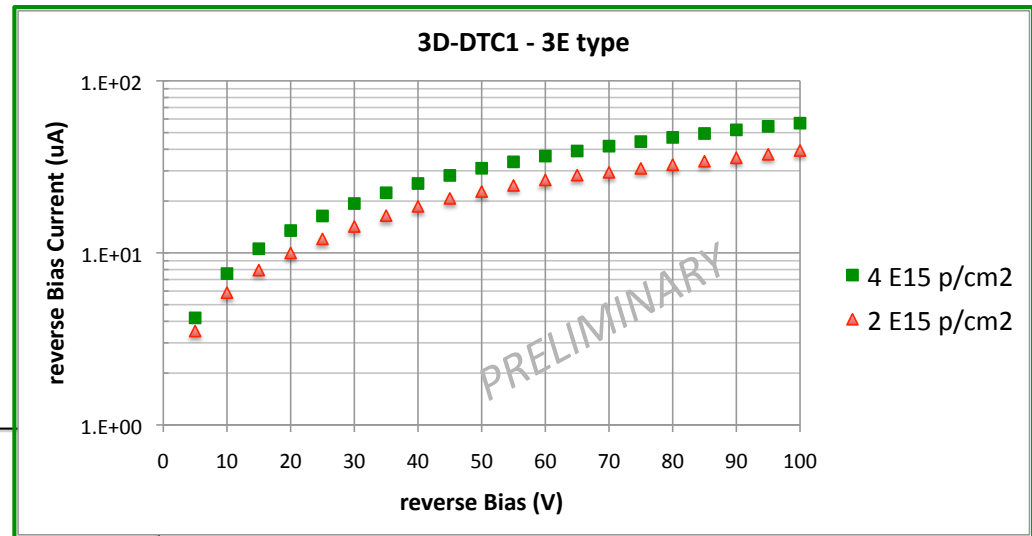
Alessandro La Rosa - CERN

24

Very preliminary results from irradi SCA

- IV characteristic of irradi sensors flip-chipped to FE-I3 (sensor&FE irradiated at the same time)
 - 24 GeV proton beam
 - $T = -14\text{C}$

Tot. fluences to be confirmed with Al dosimetry



Contribution to measurement:
F. Rivero / CERN & UniTo

Conclusions

- Development 3D-Si sensor technologies is proceeding with encouraging results at FBK-irst.
- First prototypes (ATLAS 3D-DDTC) have shown good performance
 - Lab and beam tests characterization
- ATLAS 3D-DDTC to be validated after irradiation !
 - CERN PS (24 GeV proton beam) Oct. - Nov. 2009
 - post irradi. test.: work in progress
- Development of “passing-through column” detectors is on going.
- Possible Detector technology for ATLAS-IBL and SLHC projects